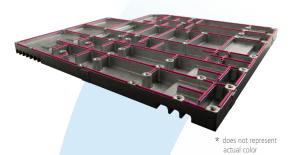


# Innovative **Technology** for a **Connected** World





## Sil35-HXP Form-In-Place

## A non-slump, single component, high flexibility, thermally curable silicone rubber.

Laird Technologies' Form-In-Place is an automated system for dispensing non-conductive and conductive elastomer EMI shielding and grounding gaskets onto metal substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, and mobile phones, as well as many other cast enclosures and packaged electronic assemblies.

#### **TYPICAL VALUES**

MATERIAL PROPERTIES	TEST METHOD	Sil35-HXP
Product Type		Single Component Silicone
Color		Transparent
Density, g/cm <sup>3</sup>		1.1
Hardness, Shore A		35
Tensile Strength, MPa	ASTM D412	4.5
Compression Set, 22 Hrs, 23°C, 25% Compression	ASTM D575	<20
Adhesion (Al), N/cm <sup>2</sup>	LT-FIP-CLE-03	285
Cure Conditions	LT-FIP-CLE-14	
Minimum Temperature		120°C
125°C, One Hour		Full Cure

Information on the product described is based on laboratory test data which Laird Technologies believes to be reliable. It is recommended that each user make their own tests to determine the suitability of Laird Technologies' products for their application.

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### global solutions: local support ™

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#### EMI-FIP-DS-Sil35-HXP 0710

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